

**Preconditioning of nonhermetic surface
mount devices prior to reliability testing**

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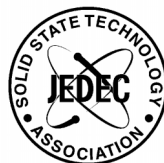
IEC PAS 62182:2000

<https://standards.iteh.ai/ci/ukg/standards/iec/ocau/fad-17c1-43b3-9b9c-8744686c45af/iec-pas-62182-2000>

PUBLICLY AVAILABLE SPECIFICATION



INTERNATIONAL
ELECTROTECHNICAL
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Reference number
IEC/PAS 62182

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EIA/JEDEC STANDARD

Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing

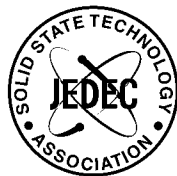
JESD22-A113-B

(Revision of Test Method A113-A)

MARCH 1999

ELECTRONIC INDUSTRIES ALLIANCE

JEDEC Solid State Technology Association



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRECONDITIONING OF NONHERMETIC SURFACE MOUNT DEVICES PRIOR TO RELIABILITY TESTING

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The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
47/1455/PAS	47/1488/RVD

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